Ching Ping Wong

List of Publications by Year in descending order

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#	Article	IF	CITATIONS
1	Low-Cost High-Performance Solid-State Asymmetric Supercapacitors Based on MnO ₂ Nanowires and Fe ₂ O ₃ Nanotubes. Nano Letters, 2014, 14, 731-736.	9.1	1,035
2	Facile Synthesis of Nitrogenâ€Ðoped Graphene via Pyrolysis of Graphene Oxide and Urea, and its Electrocatalytic Activity toward the Oxygenâ€Reduction Reaction. Advanced Energy Materials, 2012, 2, 884-888.	19.5	840
3	Hydrogenated ZnO Core–Shell Nanocables for Flexible Supercapacitors and Self-Powered Systems. ACS Nano, 2013, 7, 2617-2626.	14.6	781
4	Thermal conductivity, elastic modulus, and coefficient of thermal expansion of polymer composites filled with ceramic particles for electronic packaging. Journal of Applied Polymer Science, 1999, 74, 3396-3403.	2.6	605
5	Recent advances of conductive adhesives as a lead-free alternative in electronic packaging: Materials, processing, reliability and applications. Materials Science and Engineering Reports, 2006, 51, 1-35.	31.8	593
6	Graphene-based nitrogen self-doped hierarchical porous carbon aerogels derived from chitosan for high performance supercapacitors. Nano Energy, 2015, 15, 9-23.	16.0	531
7	Iceâ€Templated Assembly Strategy to Construct 3D Boron Nitride Nanosheet Networks in Polymer Composites for Thermal Conductivity Improvement. Small, 2015, 11, 6205-6213.	10.0	473
8	MATERIALS SCIENCE: Electronics Without Lead. Science, 2005, 308, 1419-1420.	12.6	451
9	A Combination of Boron Nitride Nanotubes and Cellulose Nanofibers for the Preparation of a Nanocomposite with High Thermal Conductivity. ACS Nano, 2017, 11, 5167-5178.	14.6	407
10	Magnetic Alignment of Hexagonal Boron Nitride Platelets in Polymer Matrix: Toward High Performance Anisotropic Polymer Composites for Electronic Encapsulation. ACS Applied Materials & Interfaces, 2013, 5, 7633-7640.	8.0	394
11	Polymer Composite with Improved Thermal Conductivity by Constructing a Hierarchically Ordered Three-Dimensional Interconnected Network of BN. ACS Applied Materials & Interfaces, 2017, 9, 13544-13553.	8.0	394
12	3D Nitrogen-doped graphene prepared by pyrolysis of graphene oxide with polypyrrole for electrocatalysis of oxygen reduction reaction. Nano Energy, 2013, 2, 241-248.	16.0	367
13	Recent Advancements in Flexible and Stretchable Electrodes for Electromechanical Sensors: Strategies, Materials, and Features. ACS Applied Materials & Interfaces, 2017, 9, 12147-12164.	8.0	359
14	Large-scale production of two-dimensional nanosheets. Journal of Materials Chemistry, 2012, 22, 13494.	6.7	351
15	Thermal behavior of silver nanoparticles for low-temperature interconnect applications. Journal of Electronic Materials, 2005, 34, 168-175.	2.2	344
16	A flexible, ultra-highly sensitive and stable capacitive pressure sensor with convex microarrays for motion and health monitoring. Nano Energy, 2020, 70, 104436.	16.0	344
17	Simple preparation of nanoporous few-layer nitrogen-doped graphene for use as an efficient electrocatalyst for oxygen reduction and oxygen evolution reactions. Carbon, 2013, 53, 130-136.	10.3	331
18	Vertically Aligned and Interconnected Graphene Networks for High Thermal Conductivity of Epoxy Composites with Ultralow Loading. Chemistry of Materials, 2016, 28, 6096-6104.	6.7	325

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19	Novel polymer-ceramic nanocomposite based on high dielectric constant epoxy formula for embedded capacitor application. Journal of Applied Polymer Science, 2002, 83, 1084-1090.	2.6	323
20	Glass transition and relaxation behavior of epoxy nanocomposites. Journal of Polymer Science, Part B: Polymer Physics, 2004, 42, 3849-3858.	2.1	318
21	Anticorrosive, Ultralight, and Flexible Carbonâ€Wrapped Metallic Nanowire Hybrid Sponges for Highly Efficient Electromagnetic Interference Shielding. Small, 2018, 14, e1800534.	10.0	310
22	Superior Capacitance of Functionalized Graphene. Journal of Physical Chemistry C, 2011, 115, 7120-7125.	3.1	307
23	Silver Nanowires: From Scalable Synthesis to Recyclable Foldable Electronics. Advanced Materials, 2011, 23, 3052-3056.	21.0	297
24	Construction of 3D Skeleton for Polymer Composites Achieving a High Thermal Conductivity. Small, 2018, 14, e1704044.	10.0	295
25	Hierarchical Silicon Etched Structures for Controlled Hydrophobicity/Superhydrophobicity. Nano Letters, 2007, 7, 3388-3393.	9.1	290
26	Nitrogen-doped hierarchically porous carbon foam: A free-standing electrode and mechanical support for high-performance supercapacitors. Nano Energy, 2016, 25, 193-202.	16.0	287
27	A Three-Dimensional Vertically Aligned Functionalized Multilayer Graphene Architecture: An Approach for Graphene-Based Thermal Interfacial Materials. ACS Nano, 2011, 5, 2392-2401.	14.6	283
28	High-Strength, Tough, Fatigue Resistant, and Self-Healing Hydrogel Based on Dual Physically Cross-Linked Network. ACS Applied Materials & Interfaces, 2016, 8, 24030-24037.	8.0	281
29	Highâ€Concentration Aqueous Dispersions of MoS ₂ . Advanced Functional Materials, 2013, 23, 3577-3583.	14.9	271
30	A Novel Conformal RFID-Enabled Module Utilizing Inkjet-Printed Antennas and Carbon Nanotubes for Gas-Detection Applications. IEEE Antennas and Wireless Propagation Letters, 2009, 8, 653-656.	4.0	267
31	Artificial nacre-like papers based on noncovalent functionalized boron nitride nanosheets with excellent mechanical and thermally conductive properties. Nanoscale, 2015, 7, 6774-6781.	5.6	265
32	Construction of a 3D-BaTiO ₃ network leading to significantly enhanced dielectric permittivity and energy storage density of polymer composites. Energy and Environmental Science, 2017, 10, 137-144.	30.8	265
33	Solvent-Assisted Thermal Reduction of Graphite Oxide. Journal of Physical Chemistry C, 2010, 114, 14819-14825.	3.1	264
34	Mechanical Chameleon through Dynamic Real-Time Plasmonic Tuning. ACS Nano, 2016, 10, 1788-1794.	14.6	262
35	Surface Functionalized Silver Nanoparticles for Ultrahigh Conductive Polymer Composites. Chemistry of Materials, 2006, 18, 2969-2973.	6.7	261
36	Facile preparation of nitrogen-doped graphene as a metal-free catalyst for oxygen reduction reaction. Physical Chemistry Chemical Physics, 2012, 14, 3381.	2.8	261

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37	Synthesis and dielectric properties of novel high-K polymer composites containing in-situ formed silver nanoparticles for embedded capacitor applications. Journal of Materials Chemistry, 2006, 16, 1543.	6.7	254
38	Amorphous nanostructured FeOOH and Co–Ni double hydroxides for high-performance aqueous asymmetric supercapacitors. Nano Energy, 2016, 21, 145-153.	16.0	254
39	Significant Enhancement of Thermal Conductivity in Bioinspired Freestanding Boron Nitride Papers Filled with Graphene Oxide. Chemistry of Materials, 2016, 28, 1049-1057.	6.7	250
40	Realizing an Allâ€Round Hydrogel Electrolyte toward Environmentally Adaptive Dendriteâ€Free Aqueous Zn–MnO ₂ Batteries. Advanced Materials, 2021, 33, e2007559.	21.0	250
41	Scalable fabrication of MnO ₂ nanostructure deposited on free-standing Ni nanocone arrays for ultrathin, flexible, high-performance micro-supercapacitor. Energy and Environmental Science, 2014, 7, 2652-2659.	30.8	247
42	Highly Sensitive Flexible Pressure Sensor Based on Silver Nanowires-Embedded Polydimethylsiloxane Electrode with Microarray Structure. ACS Applied Materials & Interfaces, 2017, 9, 26314-26324.	8.0	234
43	Interstitial Occupancy by Extrinsic Alkali Cations in Perovskites and Its Impact on Ion Migration. Advanced Materials, 2018, 30, e1707350.	21.0	233
44	Low-loss percolative dielectric composite. Applied Physics Letters, 2005, 87, 082907.	3.3	232
45	Ultralight, super-elastic and volume-preserving cellulose fiber/graphene aerogel for high-performance electromagnetic interference shielding. Carbon, 2017, 115, 629-639.	10.3	228
46	A precise numerical prediction of effective dielectric constant for polymer-ceramic composite based on effective-medium theory. IEEE Transactions on Components and Packaging Technologies, 2000, 23, 680-683.	1.3	223
47	Study on mono-dispersed nano-size silica by surface modification for underfill applications. Journal of Colloid and Interface Science, 2005, 292, 436-444.	9.4	220
48	Flexible Asymmetrical Solid-State Supercapacitors Based on Laboratory Filter Paper. ACS Nano, 2016, 10, 1273-1282.	14.6	215
49	Metal-Level Thermally Conductive yet Soft Graphene Thermal Interface Materials. ACS Nano, 2019, 13, 11561-11571.	14.6	214
50	Hollowâ€Structured Graphene–Siliconeâ€Compositeâ€Based Piezoresistive Sensors: Decoupled Property Tuning and Bending Reliability. Advanced Materials, 2017, 29, 1702675.	21.0	213
51	Mechanically robust superhydrophobicity on hierarchically structured Si surfaces. Nanotechnology, 2010, 21, 155705.	2.6	211
52	Rational Design of Nickel Hydroxideâ€Based Nanocrystals on Graphene for Ultrafast Energy Storage. Advanced Energy Materials, 2018, 8, 1702247.	19.5	211
53	Cotton-derived cellulose film as a dendrite-inhibiting separator to stabilize the zinc metal anode of aqueous zinc ion batteries. Energy Storage Materials, 2022, 44, 57-65.	18.0	211
54	Superhydrophobicity on Two-Tier Rough Surfaces Fabricated by Controlled Growth of Aligned Carbon Nanotube Arrays Coated with Fluorocarbon. Langmuir, 2005, 21, 11208-11212.	3.5	207

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55	Material characterization of a high-dielectric-constant polymer-ceramic composite for embedded capacitor for RF applications. Journal of Applied Polymer Science, 2004, 92, 2228-2231.	2.6	201
56	Amorphous Ni(OH)2 encounter with crystalline CuS in hollow spheres: A mesoporous nano-shelled heterostructure for hydrogen evolution electrocatalysis. Nano Energy, 2018, 44, 7-14.	16.0	201
57	Through-plane assembly of carbon fibers into 3D skeleton achieving enhanced thermal conductivity of a thermal interface material. Chemical Engineering Journal, 2020, 380, 122550.	12.7	201
58	Flexible and Highly Sensitive Pressure Sensor Based on Microdome-Patterned PDMS Forming with Assistance of Colloid Self-Assembly and Replica Technique for Wearable Electronics. ACS Applied Materials & Interfaces, 2017, 9, 35968-35976.	8.0	200
59	Polymer composite with enhanced thermal conductivity and mechanical strength through orientation manipulating of BN. Composites Science and Technology, 2018, 160, 127-137.	7.8	199
60	High dielectric constant polyaniline/epoxy composites via in situ polymerization for embedded capacitor applications. Polymer, 2007, 48, 1510-1516.	3.8	196
61	Anti-freezing flexible aqueous Zn–MnO ₂ batteries working at â^35 °C enabled by a borax-crosslinked polyvinyl alcohol/glycerol gel electrolyte. Journal of Materials Chemistry A, 2020, 8, 6828-6841.	10.3	196
62	Graphene paper for exceptional EMI shielding performance using large-sized graphene oxide sheets and doping strategy. Carbon, 2017, 122, 74-81.	10.3	195
63	Ultrahigh-Aspect-Ratio Boron Nitride Nanosheets Leading to Superhigh In-Plane Thermal Conductivity of Foldable Heat Spreader. ACS Nano, 2021, 15, 6489-6498.	14.6	191
64	An ultrafast, high capacity and superior longevity Ni/Zn battery constructed on nickel nanowire array film. Nano Energy, 2016, 30, 900-908.	16.0	188
65	Benzylamineâ€Treated Wideâ€Bandgap Perovskite with High Thermalâ€Photostability and Photovoltaic Performance. Advanced Energy Materials, 2017, 7, 1701048.	19.5	188
66	Recent Advances in Flip-Chip Underfill: Materials, Process, and Reliability. IEEE Transactions on Advanced Packaging, 2004, 27, 515-524.	1.6	184
67	Silver Nanoparticle-Deposited Boron Nitride Nanosheets as Fillers for Polymeric Composites with High Thermal Conductivity. Scientific Reports, 2016, 6, 19394.	3.3	184
68	Vertically Aligned and Interconnected SiC Nanowire Networks Leading to Significantly Enhanced Thermal Conductivity of Polymer Composites. ACS Applied Materials & Interfaces, 2018, 10, 9669-9678.	8.0	183
69	High-performance flexible and self-healable quasi-solid-state zinc-ion hybrid supercapacitor based on borax-crosslinked polyvinyl alcohol/nanocellulose hydrogel electrolyte. Journal of Materials Chemistry A, 2019, 7, 26524-26532.	10.3	183
70	Facile Fabrication of Superhydrophobic Octadecylamine-Functionalized Graphite Oxide Film. Langmuir, 2010, 26, 16110-16114.	3.5	180
71	A Combined Process of In Situ Functionalization and Microwave Treatment to Achieve Ultrasmall Thermal Expansion of Aligned Carbon Nanotube–Polymer Nanocomposites: Toward Applications as Thermal Interface Materials. Advanced Materials, 2009, 21, 2421-2424.	21.0	178
72	Well-Aligned Open-Ended Carbon Nanotube Architectures:Â An Approach for Device Assembly. Nano Letters, 2006, 6, 243-247.	9.1	177

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73	Highly Stretchable and Sensitive Strain Sensor Based on Facilely Prepared Three-Dimensional Graphene Foam Composite. ACS Applied Materials & Interfaces, 2016, 8, 18954-18961.	8.0	176
74	Size-dependent melting properties of tin nanoparticles. Chemical Physics Letters, 2006, 429, 492-496.	2.6	175
75	An Ultralong, Highly Oriented Nickelâ€Nanowireâ€Array Electrode Scaffold for Highâ€Performance Compressible Pseudocapacitors. Advanced Materials, 2016, 28, 4105-4110.	21.0	171
76	Covalent polymer functionalization of graphene for improved dielectric properties and thermal stability of epoxy composites. Composites Science and Technology, 2016, 122, 27-35.	7.8	171
77	Influence of interphase and moisture on the dielectric spectroscopy of epoxy/silica composites. Polymer, 2005, 46, 2297-2305.	3.8	169
78	A hybrid energy cell for self-powered water splitting. Energy and Environmental Science, 2013, 6, 2429.	30.8	162
79	Ultrathin Densified Carbon Nanotube Film with "Metal-like―Conductivity, Superior Mechanical Strength, and Ultrahigh Electromagnetic Interference Shielding Effectiveness. ACS Nano, 2020, 14, 14134-14145.	14.6	162
80	3D porous graphene with ultrahigh surface area for microscale capacitive deionization. Nano Energy, 2015, 11, 711-718.	16.0	161
81	A highly sensitive and flexible capacitive pressure sensor based on a micro-arrayed polydimethylsiloxane dielectric layer. Journal of Materials Chemistry C, 2018, 6, 13232-13240.	5.5	160
82	Learning from Natural Nacre: Constructing Layered Polymer Composites with High Thermal Conductivity. ACS Applied Materials & amp; Interfaces, 2017, 9, 33001-33010.	8.0	159
83	A review of gassing behavior in Li ₄ Ti ₅ O ₁₂ -based lithium ion batteries. Journal of Materials Chemistry A, 2017, 5, 6368-6381.	10.3	157
84	Water-dispersible graphene/polyaniline composites for flexible micro-supercapacitors with high energy densities. Nano Energy, 2015, 16, 470-478.	16.0	151
85	Recent advances in high-k nanocomposite materials for embedded capacitor applications. IEEE Transactions on Dielectrics and Electrical Insulation, 2008, 15, 1322-1328.	2.9	150
86	Preparation of highly conductive polymer nanocomposites by low temperature sintering of silver nanoparticles. Journal of Materials Chemistry, 2010, 20, 2018.	6.7	150
87	Review of Recent Advances in Electrically Conductive Adhesive Materials and Technologies in Electronic Packaging. Journal of Adhesion Science and Technology, 2008, 22, 1593-1630.	2.6	149
88	NaCl-templated synthesis of hierarchical porous carbon with extremely large specific surface area and improved graphitization degree for high energy density lithium ion capacitors. Journal of Materials Chemistry A, 2018, 6, 17057-17066.	10.3	149
89	A universal method for large-yield and high-concentration exfoliation of two-dimensional hexagonal boron nitride nanosheets. Materials Today, 2019, 27, 33-42.	14.2	149
90	Highly Conductive, Flexible, Polyurethaneâ€Based Adhesives for Flexible and Printed Electronics. Advanced Functional Materials, 2013, 23, 1459-1465.	14.9	148

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91	Enhancing the Electrical and Optoelectronic Performance of Nanobelt Devices by Molecular Surface Functionalization. Nano Letters, 2007, 7, 1323-1328.	9.1	147
92	Highly Thermally Conductive Composite Papers Prepared Based on the Thought of Bioinspired Engineering. ACS Applied Materials & Interfaces, 2016, 8, 15645-15653.	8.0	145
93	Mechanistic investigation of the graphene functionalization using p-phenylenediamine and its application for supercapacitors. Nano Energy, 2015, 17, 160-170.	16.0	143
94	Integrated paper electrodes derived from cotton stalks for high-performance flexible supercapacitors. Nano Energy, 2018, 53, 337-344.	16.0	143
95	Spray-assisted assembled spherical boron nitride as fillers for polymers with enhanced thermally conductivity. Chemical Engineering Journal, 2019, 370, 166-175.	12.7	141
96	UV and thermally stable superhydrophobic coatings from sol–gel processing. Journal of Colloid and Interface Science, 2008, 326, 465-470.	9.4	140
97	Graphene oxide nano-sheets wrapped Cu2O microspheres as improved performance anode materials for lithium ion batteries. Nano Energy, 2015, 11, 38-47.	16.0	139
98	Interfacial Engineering of Silicon Carbide Nanowire/Cellulose Microcrystal Paper toward High Thermal Conductivity. ACS Applied Materials & Interfaces, 2016, 8, 31248-31255.	8.0	139
99	Effect of Catalyst Shape and Etchant Composition on Etching Direction in Metal-Assisted Chemical Etching of Silicon to Fabricate 3D Nanostructures. ACS Nano, 2009, 3, 4033-4042.	14.6	137
100	In situ polymerization of mechanically reinforced, thermally healable graphene oxide/polyurethane composites based on Diels–Alder chemistry. Journal of Materials Chemistry A, 2014, 2, 20642-20649.	10.3	137
101	Future paper based printed circuit boards for green electronics: fabrication and life cycle assessment. Energy and Environmental Science, 2014, 7, 3674-3682.	30.8	136
102	Laser-processed graphene based micro-supercapacitors for ultrathin, rollable, compact and designable energy storage components. Nano Energy, 2016, 26, 276-285.	16.0	135
103	Lanthanide porphyrin complexes. Potential new class of nuclear magnetic resonance dipolar probe. Journal of the American Chemical Society, 1974, 96, 7149-7150.	13.7	134
104	Tunable electromagnetic properties and enhanced microwave absorption ability of flaky graphite/cobalt zinc ferrite composites. Journal of Alloys and Compounds, 2016, 662, 409-414.	5.5	134
105	Facile Preparation of Superelastic and Ultralow Dielectric Boron Nitride Nanosheet Aerogels via Freeze-Casting Process. Chemistry of Materials, 2015, 27, 5849-5855.	6.7	133
106	Wafer bonding using microwave heating of parylene intermediate layers. Journal of Micromechanics and Microengineering, 2004, 14, 625-631.	2.6	132
107	Core–shell SiO ₂ @RGO hybrids for epoxy composites with low percolation threshold and enhanced thermo-mechanical properties. Journal of Materials Chemistry A, 2014, 2, 18246-18255.	10.3	132
108	A Paper-Like Inorganic Thermal Interface Material Composed of Hierarchically Structured Graphene/Silicon Carbide Nanorods. ACS Nano, 2019, 13, 1547-1554.	14.6	131

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109	Relationship between Work of Adhesion and Contact Angle Hysteresis on Superhydrophobic Surfaces. Journal of Physical Chemistry C, 2008, 112, 11403-11407.	3.1	130
110	Fast Preparation of Printable Highly Conductive Polymer Nanocomposites by Thermal Decomposition of Silver Carboxylate and Sintering of Silver Nanoparticles. ACS Applied Materials & Interfaces, 2010, 2, 2637-2645.	8.0	130
111	Facile Preparation of Monodisperse, Impurity-Free, and Antioxidation Copper Nanoparticles on a Large Scale for Application in Conductive Ink. ACS Applied Materials & Interfaces, 2014, 6, 560-567.	8.0	129
112	Ultrafast, dry microwave synthesis of graphene sheets. Journal of Materials Chemistry, 2010, 20, 4781.	6.7	128
113	Hybridization of graphene nanosheets and carbon-coated hollow Fe ₃ O ₄ nanoparticles as a high-performance anode material for lithium-ion batteries. Journal of Materials Chemistry A, 2016, 4, 2453-2460.	10.3	128
114	<i>In situ</i> growth of Cu(OH) ₂ @FeOOH nanotube arrays on catalytically deposited Cu current collector patterns for high-performance flexible in-plane micro-sized energy storage devices. Energy and Environmental Science, 2019, 12, 194-205.	30.8	128
115	Shape-Tailorable Graphene-Based Ultra-High-Rate Supercapacitor for Wearable Electronics. ACS Nano, 2015, 9, 5636-5645.	14.6	127
116	Silicon-Based Hybrid Energy Cell for Self-Powered Electrodegradation and Personal Electronics. ACS Nano, 2013, 7, 2808-2813.	14.6	125
117	Systematic study on structural and electronic properties of diamine/triamine functionalized graphene networks for supercapacitor application. Nano Energy, 2017, 31, 183-193.	16.0	124
118	Pseudocapacitive anthraquinone modified with reduced graphene oxide for flexible symmetric all-solid-state supercapacitors. Carbon, 2018, 127, 459-468.	10.3	123
119	Growth and electrical characterization of high-aspect-ratio carbon nanotube arrays. Carbon, 2006, 44, 253-258.	10.3	121
120	Compositionâ€Tuned Wide Bandgap Perovskites: From Grain Engineering to Stability and Performance Improvement. Advanced Functional Materials, 2018, 28, 1803130.	14.9	121
121	Aligned Carbon Nanotube Stacks by Water-Assisted Selective Etching. Nano Letters, 2005, 5, 2641-2645.	9.1	120
122	Printed electrically conductive composites: conductive filler designs and surface engineering. Journal of Materials Chemistry C, 2013, 1, 4052.	5.5	120
123	Worm-like amorphous MnO2nanowires grown on textiles for high-performance flexible supercapacitors. Journal of Materials Chemistry A, 2014, 2, 595-599.	10.3	120
124	Interfacial Laserâ€Induced Graphene Enabling Highâ€Performance Liquidâ^'Solid Triboelectric Nanogenerator. Advanced Materials, 2021, 33, e2104290.	21.0	120
125	Controlled Growth of Multilayer, Few-Layer, and Single-Layer Graphene on Metal Substrates. Journal of Physical Chemistry C, 2011, 115, 5232-5238.	3.1	119
126	Achieving Significant Thermal Conductivity Enhancement via an Ice-Templated and Sintered BN-SiC Skeleton. ACS Applied Materials & Interfaces, 2020, 12, 2892-2902.	8.0	118

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127	Ice-Templated MXene/Ag–Epoxy Nanocomposites as High-Performance Thermal Management Materials. ACS Applied Materials & Interfaces, 2020, 12, 24298-24307.	8.0	117
128	Template-grown graphene/porous Fe2O3 nanocomposite: A high-performance anode material for pseudocapacitors. Nano Energy, 2015, 15, 719-728.	16.0	116
129	Syntheses and characterizations of thermally reworkable epoxy resins II. Journal of Polymer Science Part A, 2000, 38, 3771-3782.	2.3	115
130	Effects of shrinkage on conductivity of isotropic conductive adhesives. International Journal of Adhesion and Adhesives, 2000, 20, 189-193.	2.9	115
131	Synthesis and Thermal and Wetting Properties of Tin/Silver Alloy Nanoparticles for Low Melting Point Lead-Free Solders. Chemistry of Materials, 2007, 19, 4482-4485.	6.7	115
132	Enhanced thermal conductivity for Ag-deposited alumina sphere/epoxy resin composites through manipulating interfacial thermal resistance. Composites Part A: Applied Science and Manufacturing, 2018, 107, 561-569.	7.6	115
133	Highly Compressive Boron Nitride Nanotube Aerogels Reinforced with Reduced Graphene Oxide. ACS Nano, 2019, 13, 7402-7409.	14.6	115
134	Conductivity enhancement of nano silver-filled conductive adhesives by particle surface functionalization. Journal of Electronic Materials, 2005, 34, 1432-1439.	2.2	114
135	Silver/polymer nanocomposite as a high-k polymer matrix for dielectric composites with improved dielectric performance. Journal of Materials Chemistry, 2008, 18, 4821.	6.7	113
136	Triethanolamine functionalized graphene-based composites for high performance supercapacitors. Journal of Materials Chemistry A, 2015, 3, 21789-21796.	10.3	112
137	An improved methodology for determining temperature dependent moduli of underfill encapsulants. IEEE Transactions on Components and Packaging Technologies, 2000, 23, 434-439.	1.3	111
138	Flexible micro-supercapacitor based on in-situ assembled graphene on metal template at room temperature. Nano Energy, 2014, 10, 222-228.	16.0	111
139	Improving thermal conductivity through welding boron nitride nanosheets onto silver nanowires via silver nanoparticles. Composites Science and Technology, 2019, 177, 118-126.	7.8	111
140	Rational Design of a Printable, Highly Conductive Siliconeâ€based Electrically Conductive Adhesive for Stretchable Radioâ€Frequency Antennas. Advanced Functional Materials, 2015, 25, 464-470.	14.9	109
141	Facile preparation of nitrogen/sulfur co-doped and hierarchical porous graphene hydrogel for high-performance electrochemical capacitor. Journal of Power Sources, 2017, 345, 146-155.	7.8	109
142	Sea urchin-like microstructure pressure sensors with an ultra-broad range and high sensitivity. Nature Communications, 2021, 12, 1776.	12.8	109
143	Reversible Superhydrophobic–Superhydrophilic Transition of ZnO Nanorod/Epoxy Composite Films. ACS Applied Materials & Interfaces, 2012, 4, 3959-3964.	8.0	108
144	Porous octahedral PdCu nanocages as highly efficient electrocatalysts for the methanol oxidation reaction. Journal of Materials Chemistry A, 2018, 6, 3906-3912.	10.3	108

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145	Multiscale Structural Modulation of Anisotropic Graphene Framework for Polymer Composites Achieving Highly Efficient Thermal Energy Management. Advanced Science, 2021, 8, 2003734.	11.2	108
146	Variable Frequency Microwave Synthesis of Silver Nanoparticles. Journal of Nanoparticle Research, 2006, 8, 117-124.	1.9	106
147	Microstructure engineering of graphene towards highly thermal conductive composites. Composites Part A: Applied Science and Manufacturing, 2018, 112, 216-238.	7.6	106
148	Lanthanide porphyrin complexes. Evaluation of nuclear magnetic resonance dipolar probe and shift reagent capabilities. Journal of the American Chemical Society, 1976, 98, 7157-7162.	13.7	104
149	Superhydrophobic and Low Light Reflectivity Silicon Surfaces Fabricated by Hierarchical Etching. Langmuir, 2008, 24, 10421-10426.	3.5	104
150	Tubular Cu(OH) ₂ arrays decorated with nanothorny Co–Ni bimetallic carbonate hydroxide supported on Cu foam: a 3D hierarchical core–shell efficient electrocatalyst for the oxygen evolution reaction. Journal of Materials Chemistry A, 2018, 6, 10064-10073.	10.3	104
151	Ultrafast Self-Healing Nanocomposites via Infrared Laser and Their Application in Flexible Electronics. ACS Applied Materials & Interfaces, 2017, 9, 3040-3049.	8.0	103
152	Converting waste lignin into nano-biochar as a renewable substitute of carbon black for reinforcing styrene-butadiene rubber. Waste Management, 2020, 102, 732-742.	7.4	102
153	Boron nitride@graphene oxide hybrids for epoxy composites with enhanced thermal conductivity. RSC Advances, 2016, 6, 35847-35854.	3.6	101
154	1D Ni–Co oxide and sulfide nanoarray/carbon aerogel hybrid nanostructures for asymmetric supercapacitors with high energy density and excellent cycling stability. Nanoscale, 2016, 8, 16292-16301.	5.6	101
155	High performance no-flow underfills for low-cost flip-chip applications: material characterization. IEEE Transactions on Components and Packaging Technologies, 1998, 21, 450-458.	0.7	100
156	Biomimetic Creation of Hierarchical Surface Structures by Combining Colloidal Self-Assembly and Au Sputter Deposition. Langmuir, 2006, 22, 9676-9681.	3.5	100
157	Facile and scalable fabrication of three-dimensional Cu(OH) ₂ nanoporous nanorods for solid-state supercapacitors. Journal of Materials Chemistry A, 2015, 3, 17385-17391.	10.3	100
158	Mechanisms underlying the unstable contact resistance of conductive adhesives. IEEE Transactions on Electronics Packaging Manufacturing, 1999, 22, 228-232.	1.4	99
159	The hybrid nanostructure of MnCo ₂ O _{4.5} nanoneedle/carbon aerogel for symmetric supercapacitors with high energy density. Nanoscale, 2015, 7, 14401-14412.	5.6	99
160	A low-cost, printable, and stretchable strain sensor based on highly conductive elastic composites with tunable sensitivity for human motion monitoring. Nano Research, 2018, 11, 1938-1955.	10.4	99
161	Simplified Synthesis of Fluoride-Free Ti ₃ C ₂ T _{<i>x</i>} via Electrochemical Etching toward High-Performance Electrochemical Capacitors. ACS Nano, 2022, 16, 2461-2470.	14.6	99
162	Molecular Level Study of Graphene Networks Functionalized with Phenylenediamine Monomers for Supercapacitor Electrodes. Chemistry of Materials, 2016, 28, 9110-9121.	6.7	98

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164	Improving thermal conductivity of polymer composites by reducing interfacial thermal resistance between boron nitride nanotubes. Composites Science and Technology, 2018, 165, 322-330.	7.8	98
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